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- EPIC ™ (Enhanced-Performance Implanted CMOS) Submicron Process
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JEDEC Standard JESD-17
- Typical V_{OLP} (Output Ground Bounce) < 0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot)
 > 2 V at V_{CC} = 3.3 V, T_A = 25°C
- Inputs Accept Voltages to 5.5 V
- Package Options Include Plastic Small-Outline (D), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages

description

logic symbol[†]

This hex inverter contains six independent inverters designed for 2.7-V to 3.6-V V_{CC} operation. The SN74LVC04A performs the Boolean function $Y = \overline{A}$.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of these devices as translators in a mixed 3.3-V/5-V system environment.

The SN74LVC04A is characterized for operation from -40°C to 85°C.

| INPUT A | OUTPUT Y |
|------------|-------------|
| Н | L |
| L | н |

FUNCTION TABLE (each inverter)

[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

6A

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| D, DB, OR PW PACKAGE (TOP VIEW) | | | | | |
|------------------------------------|---|----------|----|---|-----------------|
| _ | | ∇ | | L | |
| 1A 🛛 | 1 | Ŭ | 14 | | V _{CC} |
| 1Y [| 2 | | 13 | | 6A |
| 2A [| 3 | | 12 | | 6Y |
| 2Y [| 4 | | 11 | | 5A |
| 3A [| 5 | | 10 | | 5Y |
| 3Y [| 6 | | 9 | | 4A |
| GND [| 7 | | 8 | | 4Y |
| | | | | | |

(

2

4

6

10

12

1Y

2Y

-8 3Y

4Y

5Y

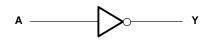
6Y

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logic diagram, each inverter (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

| Supply voltage range, V _{CC} | | –0.5 V to 6.5 V |
|--|------------|-----------------------------------|
| Input voltage range, V _I (see Note 1) | | –0.5 V to 6.5 V |
| Output voltage range, V _O (see Notes 1 and 2) | | –0.5 V to V _{CC} + 0.5 V |
| Input clamp current, IIK (VI < 0) | | |
| Output clamp current, I_{OK} (V _O < 0 or V _O > V _{CO} | с) | ±50 mA |
| Continuous output current, $I_O (V_O = 0 \text{ to } V_{CC})$ | | ±50 mA |
| Continuous current through V _{CC} or GND | | |
| Package thermal impedance, θ_{JA} (see Note 3): | | |
| | DB package | 158°C/W |
| | PW package | 170°C/W |
| Storage temperature range, T _{stg} | · · · · | –65°C to 150°C |

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The value of V_{CC} is provided in the recommended operating conditions table.

3. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 4)

| | | | MIN | MAX | UNIT | |
|----------------|--------------------------------|--|-------------|-----|------|--|
| Vaa | Operating | Operating | 2 | 3.6 | V | |
| Vcc | Supply voltage | Data retention only | 1.5 | | v | |
| VIH | High-level input voltage | $V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$ | 2 | | V | |
| VIL | Low-level input voltage | $V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$ | | 0.8 | V | |
| VI | Input voltage | | 0 | 5.5 | V | |
| VO | Output voltage | | 0 | VCC | V | |
| lau | High-level output current | $V_{CC} = 2.7 V$ | | -12 | mA | |
| ЮН | rightever output current | V _{CC} = 3 V | | -24 | 4 | |
| | Low-level output current | $V_{CC} = 2.7 V$ | 2.7 V 12 mA | | mA | |
| IOL | | V _{CC} = 3 V | | 24 | ШA | |
| Τ _Α | Operating free-air temperature | | -40 | 85 | °C | |

NOTE 4: Unused inputs must be held high or low to prevent them from floating.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | v _{cc} † | MIN | түр† | MAX | UNIT | |
|-----------------|--|-------------------|----------------------|------|------|------|--|
| | I _{OH} = -100 μA | 2.7 V to 3.6 V | V _{CC} -0.2 | | | | |
| Maria | 1 | 2.7 V | 2.2 | | | V | |
| ∨он | $I_{OH} = -12 \text{ mA}$ | 3 V | 2.4 | | | v | |
| | $I_{OH} = -24 \text{ mA}$ | 3 V | 2.2 | | | | |
| | I _{OL} = 100 μA | 2.7 V to 3.6 V | | | 0.2 | | |
| V _{OL} | I _{OL} = 12 mA | 2.7 V | | | 0.4 | V | |
| | I _{OL} = 24 mA | 3 V | | | 0.55 | | |
| lj | $V_{I} = 5.5 V \text{ or GND}$ | 3.6 V | | | ±5 | μA | |
| ICC | $V_{I} = V_{CC} \text{ or GND}, \qquad I_{O} = 0$ | 3.6 V | | | 10 | μA | |
| ∆ICC | One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND | 2.7 V to 3.6 V | | | 500 | μA | |
| Ci | $V_I = V_{CC}$ or GND | 3.3 V | | 5 | | pF | |

[†] All typical values are at V_{CC} = 3.3 V, T_A = 25° C.

switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | = V _{CC} ± 0.3 | 3.3 V 3 V | V _{CC} = | 2.7 V | UNIT |
|---------------------------------|-----------------|----------------|----------------------------|--------------|-------------------|-------|------|
| | | MIN | MAX | MIN | MAX | | |
| ^t pd | А | Y | 1 | 4.5 | | 5.5 | ns |
| ^t sk(o) [‡] | | | | 1 | | | ns |

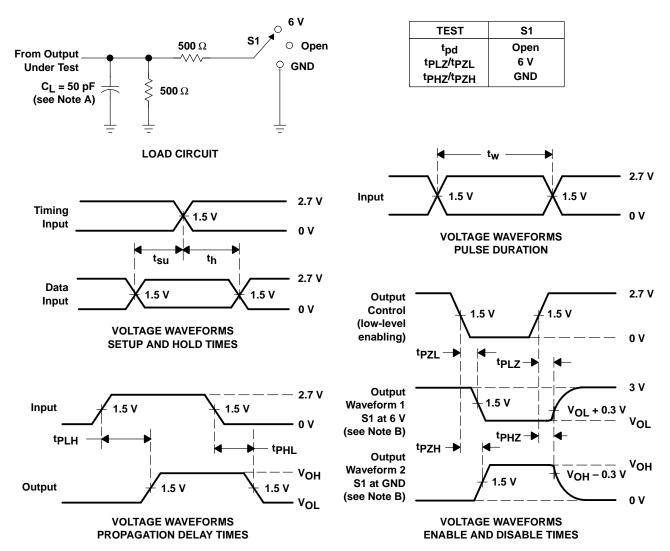
[‡]Skew between any two outputs of the same package switching in the same direction. This parameter is warranted but not production tested.

operating characteristics, V_{CC} = 3.3 V, T_A = 25°C

| | PARAMETER TEST CONDITIONS | | TYP | UNIT | | |
|---|---------------------------|--|-------------------------|------------|---|----|
| С | pd | Power dissipation capacitance per inverter | C _L = 50 pF, | f = 10 MHz | 8 | pF |



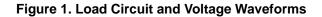
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PARAMETER MEASUREMENT INFORMATION

NOTES: A. CI includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_Q = 50 Ω, t_f ≤ 2.5 ns, t_f ≤ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. tpLH and tpHL are the same as t_{pd} .





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